

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPT210N25NFD	**Issued**	24. February 2022
MA#	MA005700558		
Package	PG-HSOF-8-1	**Weight***	776.81 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.025	0.90	0.90	9043	9043
leadframe	inorganic material	phosphorus	7723-14-0	0.126	0.02		162	
	non noble metal	iron	7439-89-6	0.421	0.05		541	
	non noble metal	copper	7440-50-8	420.040	54.07	54.14	540728	541431
wire	non noble metal	aluminium	7429-90-5	19.207	2.47	2.47	24726	24726
encapsulation	inorganic material	zincoxide	1314-13-2	3.169	0.41		4080	
	miscellaneous	miscellaneous	-	12.676	1.63		16318	
	plastics	epoxy resin	-	47.536	6.12		61194	
	inorganic material	silicondioxide	60676-86-0	253.524	32.64	40.80	326368	407960
leadfinish	non noble metal	tin	7440-31-5	6.479	0.83	0.83	8340	8340
plating	inorganic material	phosphorus	7723-14-0	0.001			2	
	non noble metal	nickel	7440-02-0	0.526	0.07	0.07	677	679
solder	non noble metal	tin	7440-31-5	0.122	0.02		156	
	noble metal	silver	7440-22-4	0.152	0.02		196	
	non noble metal	lead	7439-92-1	5.802	0.75	0.79	7469	7821
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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